

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IQE006NE2LM5CG	**Issued**	08. April 2022
MA#	MA005709870		
Package	PG-TTFN-9-1	**Weight***	43.33 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.896	2.07	2.07	20691	20691
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		76	
	non noble metal	zinc	7440-66-6	0.013	0.03		303	
	non noble metal	iron	7439-89-6	0.263	0.61		6065	
	non noble metal	copper	7440-50-8	10.669	24.62	25.27	246248	252692
encapsulation	organic material	carbon black	1333-86-4	0.029	0.07		668	
	plastics	epoxy resin	-	1.491	3.44		34417	
	inorganic material	silicondioxide	60676-86-0	12.957	29.91	33.42	299059	334144
leadfinish	non noble metal	tin	7440-31-5	0.474	1.09	1.09	10948	10948
plating	noble metal	silver	7440-22-4	0.296	0.68	0.68	6839	6839
solder	non noble metal	tin	7440-31-5	0.026	0.06		596	
	noble metal	silver	7440-22-4	0.032	0.07		745	
	non noble metal	lead	7439-92-1	1.234	2.85	2.98	28475	29816
heat sink clip	inorganic material	phosphorus	7723-14-0	0.004	0.01		102	
	non noble metal	iron	7439-89-6	0.015	0.03		340	
	non noble metal	copper	7440-50-8	14.697	33.93	33.97	339224	339666
clip attach	noble metal	silver	7440-22-4	0.006	0.01		130	
	non noble metal	tin	7440-31-5	0.011	0.03		260	
	non noble metal	lead	7439-92-1	0.209	0.48	0.52	4814	5204
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com